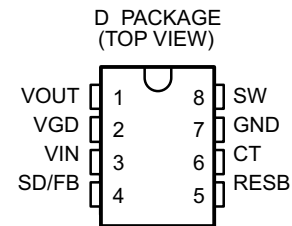
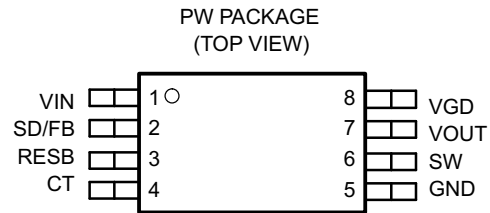


LOW-POWER SYNCHRONOUS BOOST CONVERTER

FEATURES

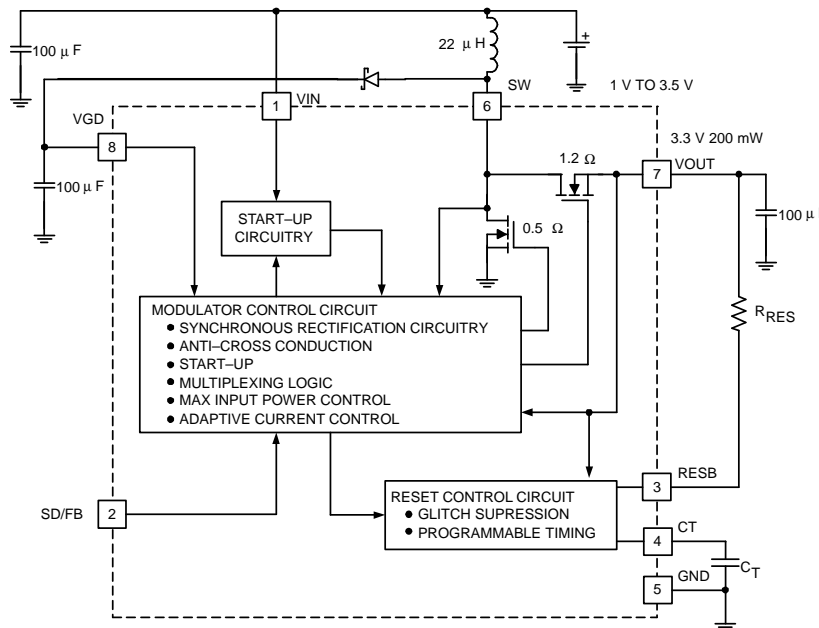
- 1 V Input Voltage Operation Start-Up Ensured Under Full Load on Main Output, and Operation Down to 0.5 V
- 200 mW Output Power at Battery Voltages as Low as 0.8 V
- Secondary 7 V Supply from a Single Inductor
- Output Fully Disconnected in Shutdown
- Adaptive Current Mode Control for Optimum Efficiency
- High Efficiency Over Wide Operating Range
- 6 μ A Shutdown Supply Current
- Output Reset Function with Programmable Reset Period



DESCRIPTION

The UCCx9411 family of low-input voltage, single-inductor-boost converters is optimized to operate from a single or dual alkaline cell, and steps up to a 3.3 V, 5 V, or adjustable output at 200 mW. The UCCx9411 family also provides an auxiliary 7 V output, primarily for the gate-drive supply, which can be used for applications requiring an auxiliary output, such as 5 V, by linear regulating. The primary output starts up under full load at input voltages typically as low as 0.8 V with a ensured max of 1 V, and operates down to 0.5 V once the converter is operating, thereby maximizing battery usage.

SIMPLIFIED BLOCK DIAGRAM AND APPLICATION CIRCUIT



A. Pinout shown is for the TSSOP Package. Consult Package Descriptions for the SOIC configurations.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DESCRIPTION (CONTINUED)

The UCCx9411 family is designed to accommodate demanding applications such as pagers and cell phones that require high efficiency over a wide operating range of several milliwatts to a couple of hundred milli-watts. High efficiency at low output current is achieved by optimizing switching and conduction losses with a low total quiescent current. At higher output current, the 0.5 Ω switch and 1.2 Ω synchronous rectifier along with continuous mode conduction provide high power efficiency. The wide input voltage range of the UCCx9411 family can accommodate other power sources such as NiCd and NiMH.

The UCCx9411 family also provides shutdown control. Packages available are the 8-pin SOIC (D) and 8-pin TSSOP (PW) to optimize board space.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾⁽²⁾

		VALUE/UNIT
V _{IN}	Input voltage	-0.3 V to 10 V
SD	Input voltage	-0.3 V to V _{IN}
V _{GD}	Input voltage	-0.3 V to 14 V
SW	Input voltage	-0.3 V to 15 V
V _{OUT}	Output voltage	-0.3 V to 10 V

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Currents are positive into, negative out of the specific terminal. Consult Packaging Section of the *Portable Products Data Book* (SLUD001) for thermal limitations and considerations of packages.

available options

T _J	PACKAGE PW ⁽¹⁾			PACKAGE D ⁽¹⁾		
	OUTPUT VOLTAGE			OUTPUT VOLTAGE		
	ADJ	3.3 V	5 V	ADJ	3.3 V	5 V
-40°C to 85°C	29411PW	29412PW	29413PW	29411D	29412D	29413D
0°C to 70°C	39411PW	39412PW	39413PW	39411D	39412D	39413D

- (1) The UCC39411, UCC39412 and UCC39413 is available in tape and reel. Add TR suffix to device type (e.g. UCC39411PWTR or UCC39411DTR) to order quantities of 2000 devices per reel (PW package) or 2500 devices per reel (D package).

ELECTRICAL CHARACTERISTICS

T_J = 0°C to 70°C for the UCC3941x, T_J = -40°C to 85°C for the UCC2941x, V_{IN} = 1.25 V for UCC39411, UCC39412, V_{IN} = 2.5 V for the UCC39413, T_A = T_J

PARAMETER	TEST CONDITIONS	UCC3941x			UCC2941x			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
INPUT VOLTAGE SECTION								
Minimum start-up voltage	No external VGD load, T _J = 25°C, I _{OUT} = 60 mA ⁽¹⁾		0.8	1		0.8	1	V
	No external VGD load, I _{OUT} = 60 mA ⁽¹⁾		0.9	1.1		1.2	1.4	V
Minimum dropout voltage	No external VGD load, I _{OUT} = 10 mA ⁽¹⁾			0.5			0.7	V
Input voltage range			1.1	3.2		1.3	3.2	V
Quiescent supply current	See ⁽²⁾		6	12		8	16	μA

- (1) Ensured by design. Not production tested.
- (2) For the UCC39411 FB = 1.306 V, VGD = 7.7 V, For the UCC39412 V_{OUT} = 3.5 V and VGD = 7.7 V, For the UCC39413 V_{OUT} = 5.3 V, VGD=9.3 V.

ELECTRICAL CHARACTERISTICS (continued)

$T_J = 0^\circ\text{C}$ to 70°C for the UCC3941x, $T_J = -40^\circ\text{C}$ to 85°C for the UCC2941x, $V_{IN} = 1.25\text{ V}$ for UCC39411, UCC39412, $V_{IN} = 2.5\text{ V}$ for the UCC39413, $T_A = T_J$

PARAMETER	TEST CONDITIONS	UCC3941x			UCC2941x			UNITS	
		MIN	TYP	MAX	MIN	TYP	MAX		
Supply current at shutdown	SD = GND		6	12		8	16	μA	
OUTPUT SECTION									
Quiescent supply current	See ⁽²⁾		15	28		20	37	μA	
Supply current at shutdown	SD = GND		3	6		5	10	μA	
Regulation voltage (UCC39412)	$1\text{ V} < V_{IN} < 3\text{ V}$	3.2	3.3	3.39	3.15	3.3	3.45	V	
	$1\text{ V} < V_{IN} < 3\text{ V}$, $0\text{ mA} < I_{OUT} < 60\text{ mA}^{(1)}$	3.17	3.3	3.43	3.11	3.3	3.5	V	
Regulation voltage (UCC39413)	$1\text{ V} < V_{IN} < 5\text{ V}$	4.85	5	5.15	4.78	5	5.23	V	
	$1\text{ V} < V_{IN} < 5\text{ V}$, $0\text{ mA} < I_{OUT} < 60\text{ mA}^{(1)}$	4.8	5	5.2	4.71	5	5.3	V	
ADJ voltage (UCC39411)	$1\text{ V} < V_{IN} < 3\text{ V}$	1.212	1.25	1.288	1.194	1.25	1.306	V	
Maximum output voltage (UCCx9411)				5.5			5.5	V	
VGD OUTPUT SECTION									
Quiescent supply current	See ⁽²⁾		20	40		27	55	μA	
Supply current at shutdown	SD = GND		20	40		27	55	μA	
Regulation voltage (UCC39411/2)	$1\text{ V} < V_{IN} < 3\text{ V}$	6.3	7	7.7	6.3	7	7.7	V	
	$1\text{ V} < V_{IN} < 3\text{ V}$, $0\text{ mA} < I_{OUT} < 10\text{ mA}^{(1)}$	6.3	7	7.7	6.3	7	7.7	V	
Regulation voltage (UCC39413)	$1\text{ V} < V_{IN} < 5\text{ V}$	7.7	8.5	9.3	7.7	8.5	9.3	V	
	$1\text{ V} < V_{IN} < 5\text{ V}$, $0\text{ mA} < I_{OUT} < 10\text{ mA}^{(3)}$	7.7	8.5	9.3	7.7	8.5	9.3	V	
INDUCTOR CHARGING SECTION (L = 22 μH)									
Peak discontinuous current	Operating range, L = 22 μH	180	250	300	180	250	300	mA	
Peak continuous current		385	550	715	385	550	715	mA	
Charge switch $R_{DS(on)}$	D package		0.5	0.75		0.6	0.85	Ω	
Current limit delay	See ⁽³⁾		50			50		ns	
SYNCHRONOUS RECTIFIER SECTION									
Rectifier $R_{DS(on)}$	D package		1.2	1.8		1.4	2.16	Ω	
SHUTDOWN SECTION									
Threshold		0.4	0.6	0.8	0.2	0.6	0.9	V	
Input bias current	SD = GND		2	5	15		2	5	μA
	SD = 1.25 V			5	20		20	100	nA
RESET SECTION									
Threshold (UCC39411)		1.08	1.125	1.17	1.07	1.125	1.18	V	
Threshold (UCC39412)		2.85	2.97	3.09	2.83	2.97	3.11	V	
Threshold (UCC39413)		4.32	4.5	4.68	4.3	4.5	4.7	V	
Reset period	$C_T = 0.15\text{ }\mu\text{F}$	113	188	300	94	188	300	ms	
V_{OUT} to reset delay	V_{OUT} falling at $-1\text{ mV}/\mu\text{s}^{(3)}$		60			60		μs	
Sink current		1	20		1	20		mA	
Output low voltage	$I_{OUT} = 500\text{ }\mu\text{A}$			0.1			0.1	V	
Output leakage				0.5			0.5	μA	

(3) Ensured by design. Not production tested.

PIN ASSIGNMENTS

VIN: Input voltage to supply the IC during start-up. After the output is running the IC draws power from VOUT or VGD.

SW: An inductor is connected between this pin and VIN. The VGD (gate drive supply) flyback diode is also connected to this pin. When servicing the main output supply this pin pulls low, charging the inductor, then shuts off dumping the energy through the synchronous rectifier to the output. When servicing the VGD supply, the internal synchronous rectifier stays off and the energy is diverted to VGD through the flyback diode. During discontinuous portions of the inductor current, a MOSFET resistively connects VIN to SW damping excess circulating energy to eliminate undesired high-frequency ringing.

VGD: The VGD pin, which is coarsely regulated around 7 V (8.5 V for the UCC39413), is primarily used for the gate drive supply for the power switches in the IC. This pin can be loaded with up to 10 mA as long as it does not present a load at voltages below 2 V (this ensures proper start-up of the IC). The VGD supply can go as low as 6.3 V without interfering with the servicing of the main output. When below 6.3 V, VGD has the highest priority.

VOUT: Main output voltage (3.3 V, 5 V, or adjustable), has highest priority in the multiplexing scheme, as long as VGD is above the critical level of 6.3 V. Startup at full load is achievable at input voltages down to 1 V.

CT: This pin provides the timer for determining the reset period. The period is controlled by placing a capacitor to ground of value $C = (0.81e^{-6}) \times t$ where t is the desired reset period.

RESB: This pin provides an active low signal to alert the user when the main output voltage falls below 10% of its targeted value. The open-drain output can be used to reset a microcontroller that may be powered off of the main output voltage.

SD/FB: For the UCC39411, this pin is used to adjust the output voltage via a resistive divider from VOUT. It also serves as the shutdown pin for all three versions. Pulling this pin low provides a shutdown signal to the IC.

GND: Ground of the IC.

APPLICATION INFORMATION

OPERATION

A detailed block diagram of the UCC39411 is shown in Figure 1. Unique control circuitry provides high-efficiency power conversion for both light and heavy loads by transitioning between discontinuous and continuous conduction based on load conditions. Figure 2 depicts converter waveforms for the application circuit shown in Figure 3. A single 22 μ H inductor provides the energy pulses required for a highly efficient 3.3 V converter at up to 200 mW output power.

At time t1, the 3.3 V output voltage has dropped below its lower threshold, and the inductor is charged with an on time determined by: $t_{ON} = 5.5 \mu\text{s}/V_{IN}$. For a 1.25 V input and a 22 μ H inductor, the resulting peak current is approximately 250 mA. At time t2, the inductor begins to discharge with a minimum off time of approximately 1 ms. Under lightly loaded conditions, the amount of energy delivered in this single pulse satisfies the voltage-control loop, and the converter does not command any more energy pulses until the output again drops below the lower-voltage threshold.

At time t3, the VGD supply drops below its lower threshold, but the output voltage is still above its threshold point. This results in an energy pulse to the gate-drive supply at t4. In some cases, a single pulse supplied to VGD is insufficient to raise the VGD voltage level enough to satisfy the voltage loop. Under this condition, multiple pulses are supplied to VGD. Note that when the UCC3941x is servicing VGD only, the IC maintains a discontinuous mode of operation. After time t4, the 3.3 V output drops below its threshold and requests to be serviced once the VGD cycle has completed, which occurs at time t5.

Time t6 represents a transition between light load and heavy load. A single energy pulse is not sufficient to force the output voltage above its upper threshold before the minimum off time has expired and a second charge cycle is commanded. Since the inductor current does not reach zero in this case, the peak current is greater than 250 mA at the end of the next charge on time. The result is a ratcheting of inductor current until either the output voltage is satisfied, or the converter reaches its set current limit. At time t7, the gate drive voltage has dropped below its 7 V threshold but the converter continues to service the output because it has higher priority unless VGD drops below about 6.3 V.

Between time t7 and t8, the converter reaches its peak current limit.

Once the peak current is reached, the converter operates in continuous mode with approximately 60 mA of inductor current ripple. At time t8, the 3.3 V output is satisfied and the converter can service the gate drive voltage, VGD, which occurs at time t9.

APPLICATION INFORMATION (continued)

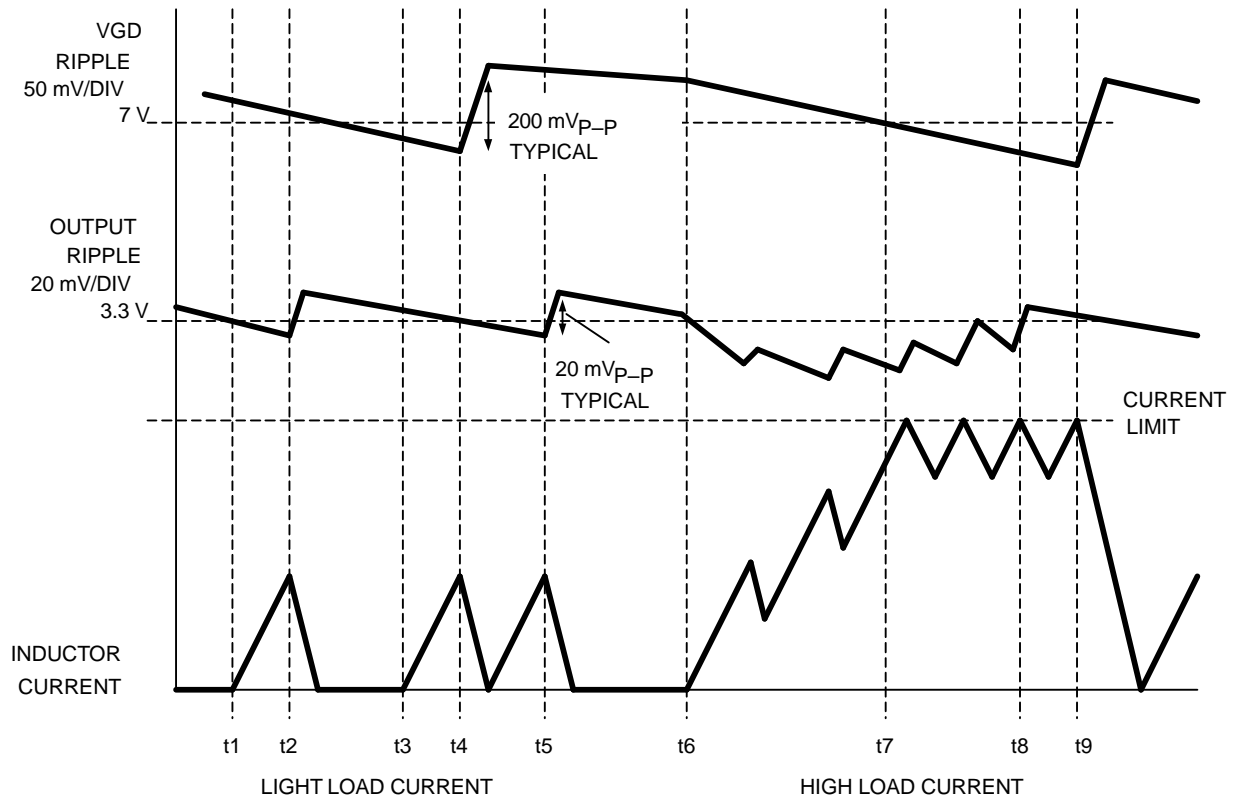
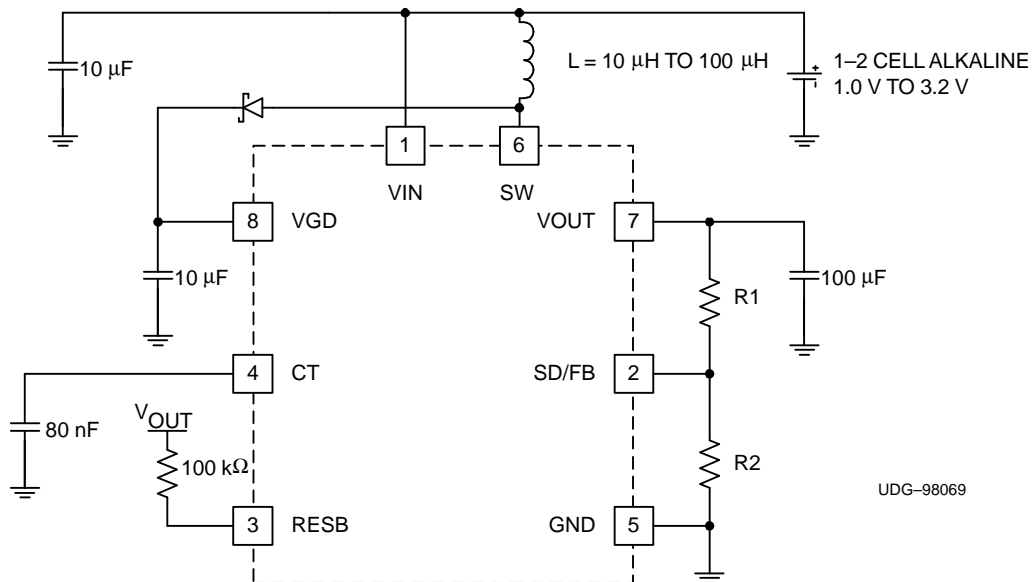


Figure 2. Inductor Current and Output Ripple Waveforms



A. Pinout shown is for the TSSOP package. Consult Package Description for the SOIC configuration.

Figure 3. Low Power Synchronous Boost Converter ADJ Version -200 mW

SHUTDOWN CONTROL

Shutdown of the UCC3941x is controlled via the interface with the SD/FB pin. Pulling the SD/FB pin low, for all

APPLICATION INFORMATION (continued)

versions, causes the IC to go into shutdown. In the UCC39412 and UCC39413, the SD/FB pin is used solely as a shutdown function. Therefore, the SD/FB pin for the UCC39412 and UCC39413 can be directly controlled using conventional CMOS or transistor to transistor logic (TTL) technology. For the UCC39411, interface into the SD/FB is slightly more complicated due to the added feedback function. When feeding back the output voltage to the SD/FB pin on the UCC39411, the IC requires a Thevenin impedance of at least 200 k Ω (500 k Ω for industrial/military applications) to ground. Then, to accomplish shutdown of the IC, an open-drain device may be used.

COMPONENT SELECTION INDUCTOR SELECTION

An inductor value of 22 μ H works well in most applications, but values between 10 μ H to 100 μ H are also acceptable. Lower value inductors typically offer lower ESR and smaller physical size. Due to the nature of the *bang-bang* controllers, larger inductor values typically result in larger overall voltage ripple, because once the output voltage level is satisfied the converter goes discontinuous, resulting in the residual energy of the inductor causing overshoot.

It is recommended to keep the ESR of the inductor below 0.15 Ω for 200 mW applications.

OUTPUT CAPACITOR SELECTION

Once the inductor value is selected, the capacitor value determines the ripple of the converter. The worst case peak-to-peak ripple of a cycle is determined by two components, one is due to the charge storage characteristic, and the other is the ESR of the capacitor. The worst case ripple occurs when the inductor is operating at max current and is expressed as follows:

$$\Delta V = \frac{(I_{CL})^2 L}{2C(V_O - V_I)} + I_{CL} C_{ESR} \quad (1)$$

- I_{CL} = the peak inductor current = 550 mA
- ΔV = Output ripple
- V_O = Output voltage
- V_I = Input voltage
- C_{ESR} = ESR of the output capacitor

INPUT CAPACITOR SELECTION

Since the UCCx9411 family does not require a large decoupling capacitor on the input voltage to operate properly, a 10 μ F cap is sufficient for most applications. Optimum efficiency occurs when the capacitor value is large enough to decouple the source impedance, this usually occurs for capacitor values in excess of 100 μ F.

RESET OPERATION

A reset function is provided to prevent the microprocessor from executing code during undervoltage conditions, typically during power up or power down. The reset voltage threshold is fixed at 90% of the output voltage for all versions of the UCCx941x. To prevent erratic operation in noisy environments, a glitch filter is provided.

To allow sufficient time for the microprocessor clock to stabilize, a user-programmable reset period is provided. The reset period, the time from the output voltage rising above 90% of nominal to RESB going high, is programmed via an external capacitor connected to the CT pin.

The reset period is defined as:

$$t_{RP} = C \times 1.25$$

where C is in μ F, and t_{RP} is in seconds.

A typical reset profile during power up is shown in [Figure 4](#) and power down in [Figure 5](#).

TYPICAL CHARACTERISTICS

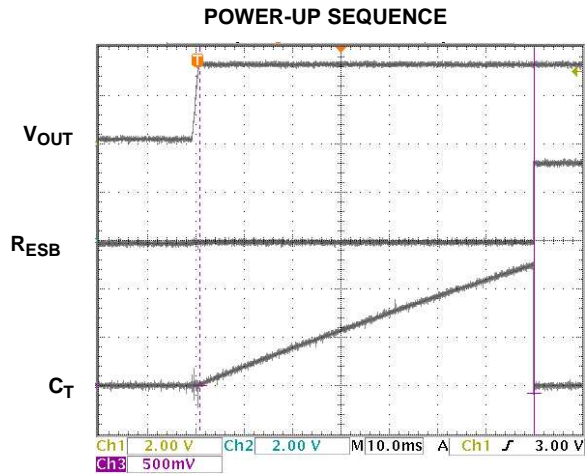


Figure 4.

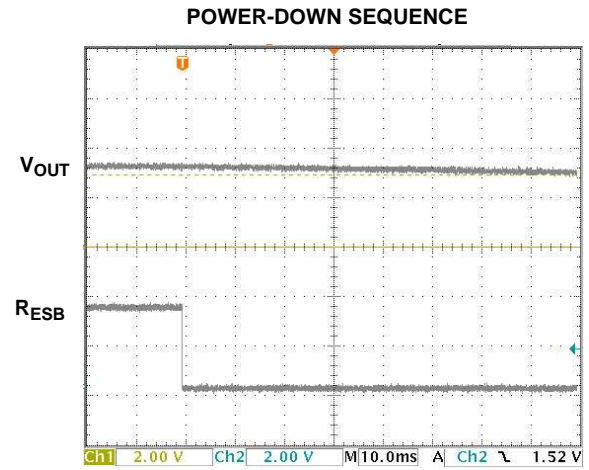


Figure 5.

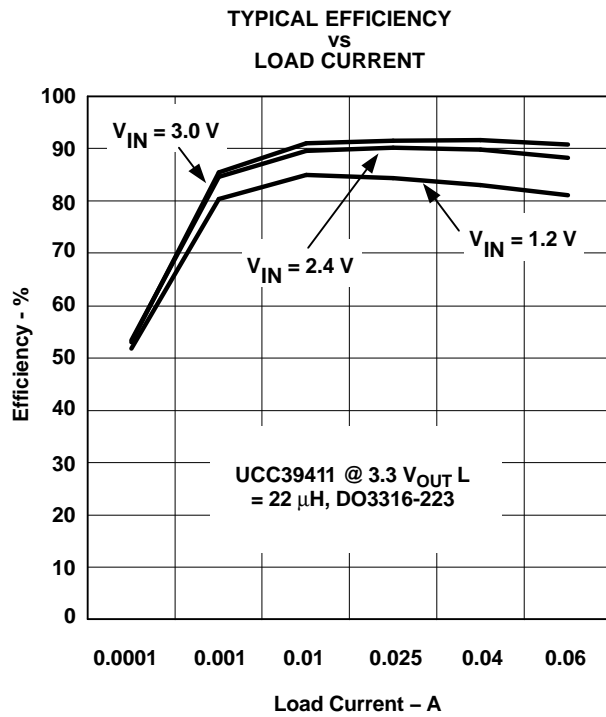


Figure 6.

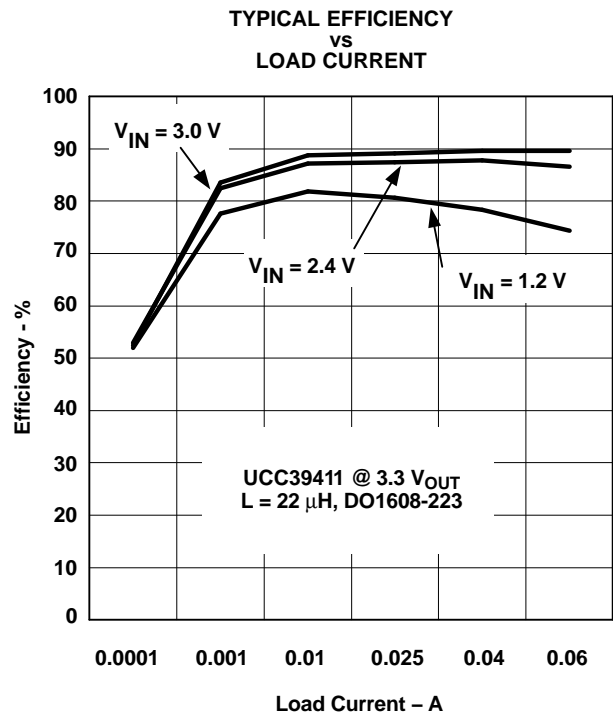


Figure 7.

TYPICAL CHARACTERISTICS (continued)

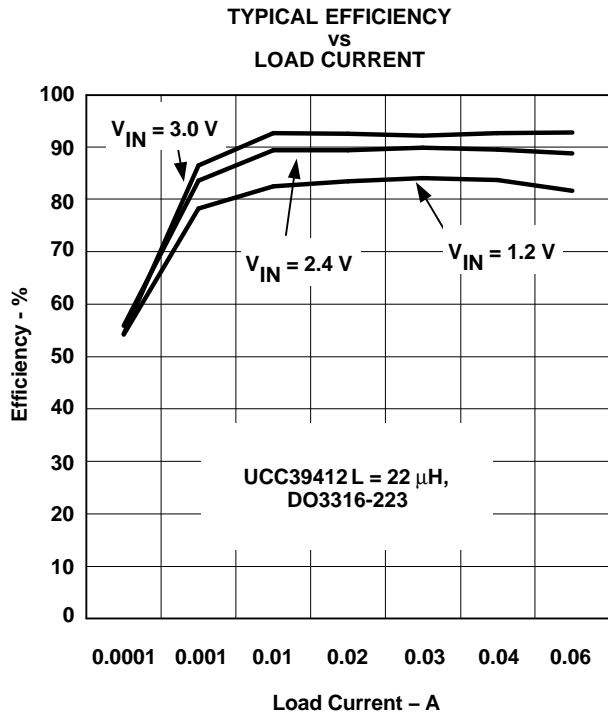


Figure 8.

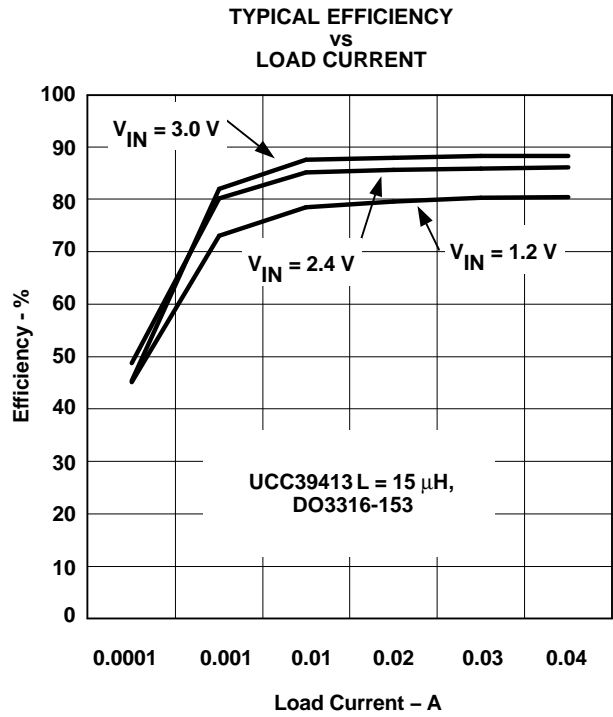


Figure 9.

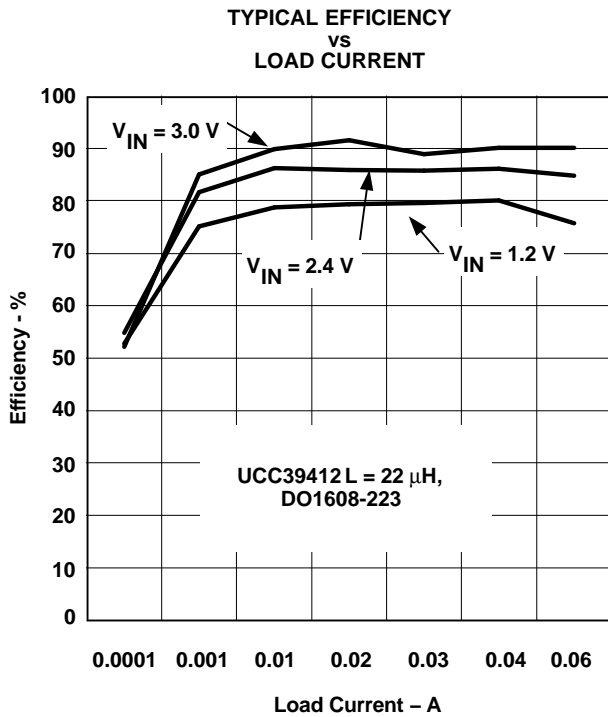


Figure 10.

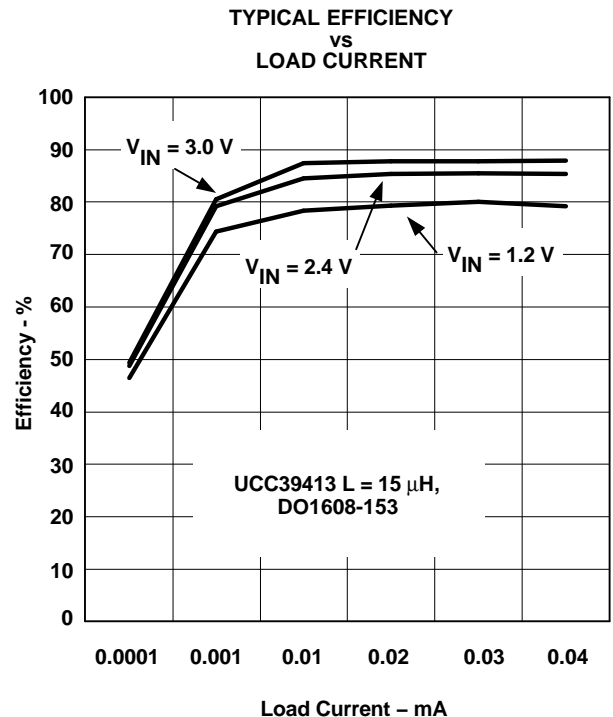


Figure 11.

TYPICAL CHARACTERISTICS (continued)

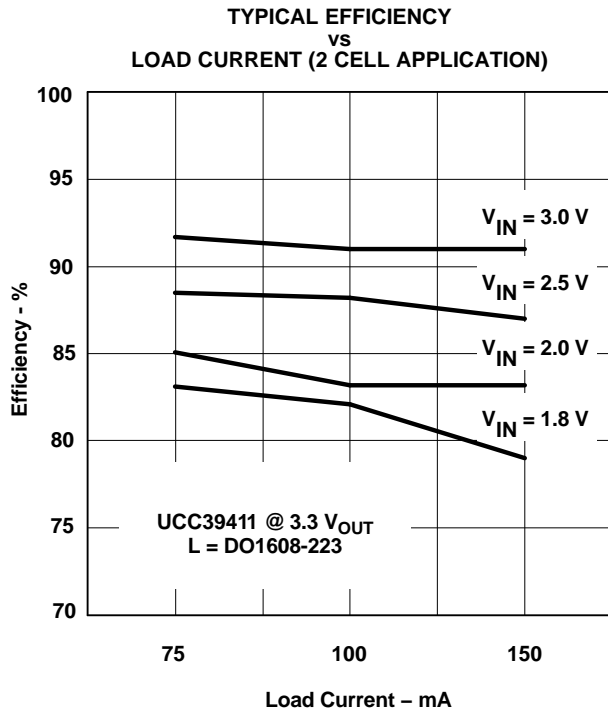


Figure 12.

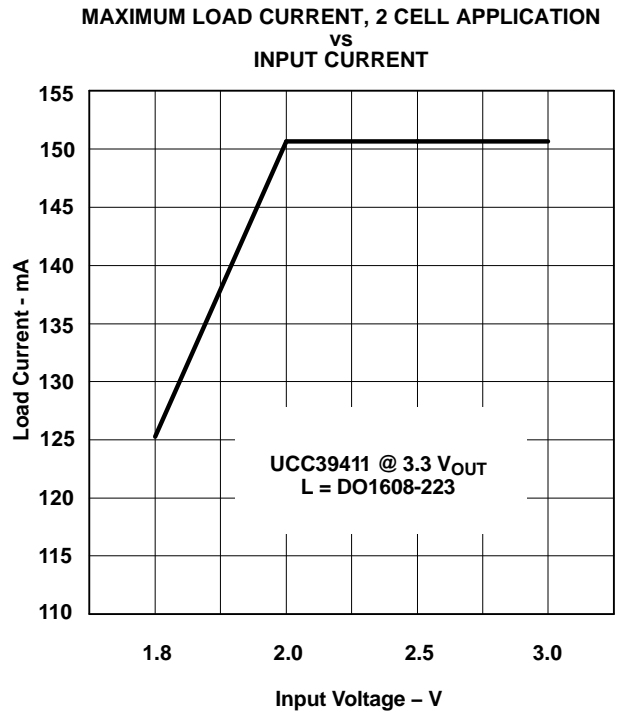


Figure 13.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
UCC29411D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC29411DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC29412PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR	Purchase Samples
UCC29412PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR	Purchase Samples
UCC39411D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39411DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39411N	LIFEBUY	PDIP	P	8		TBD	Call TI	Call TI	Samples Not Available
UCC39411NG4	LIFEBUY	PDIP	P	8		TBD	Call TI	Call TI	Samples Not Available
UCC39411PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39411PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39412PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39412PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39412PWTR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39412PWTRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39413D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
UCC39413DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

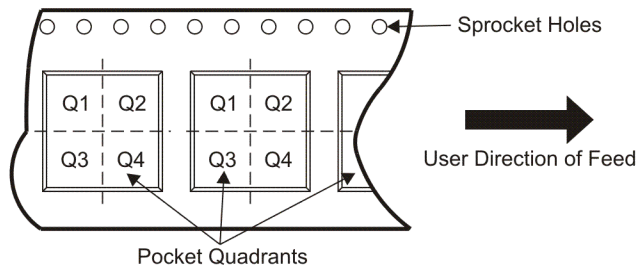
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC39412PWTR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC39412PWTR	TSSOP	PW	8	2000	346.0	346.0	29.0

P (R-PDIP-T8)

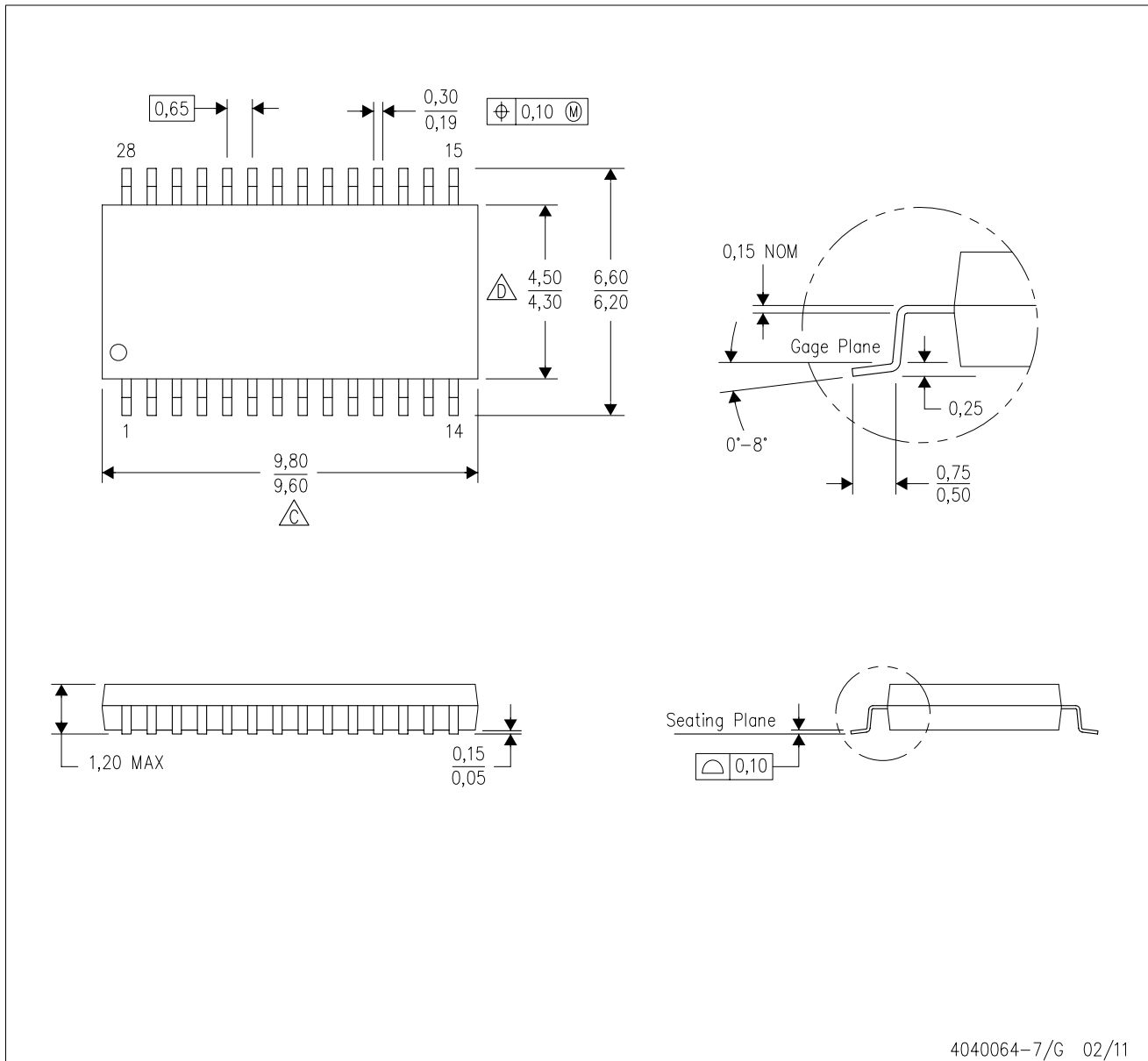
PLASTIC DUAL-IN-LINE PACKAGE



4040082/E 04/2010

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE

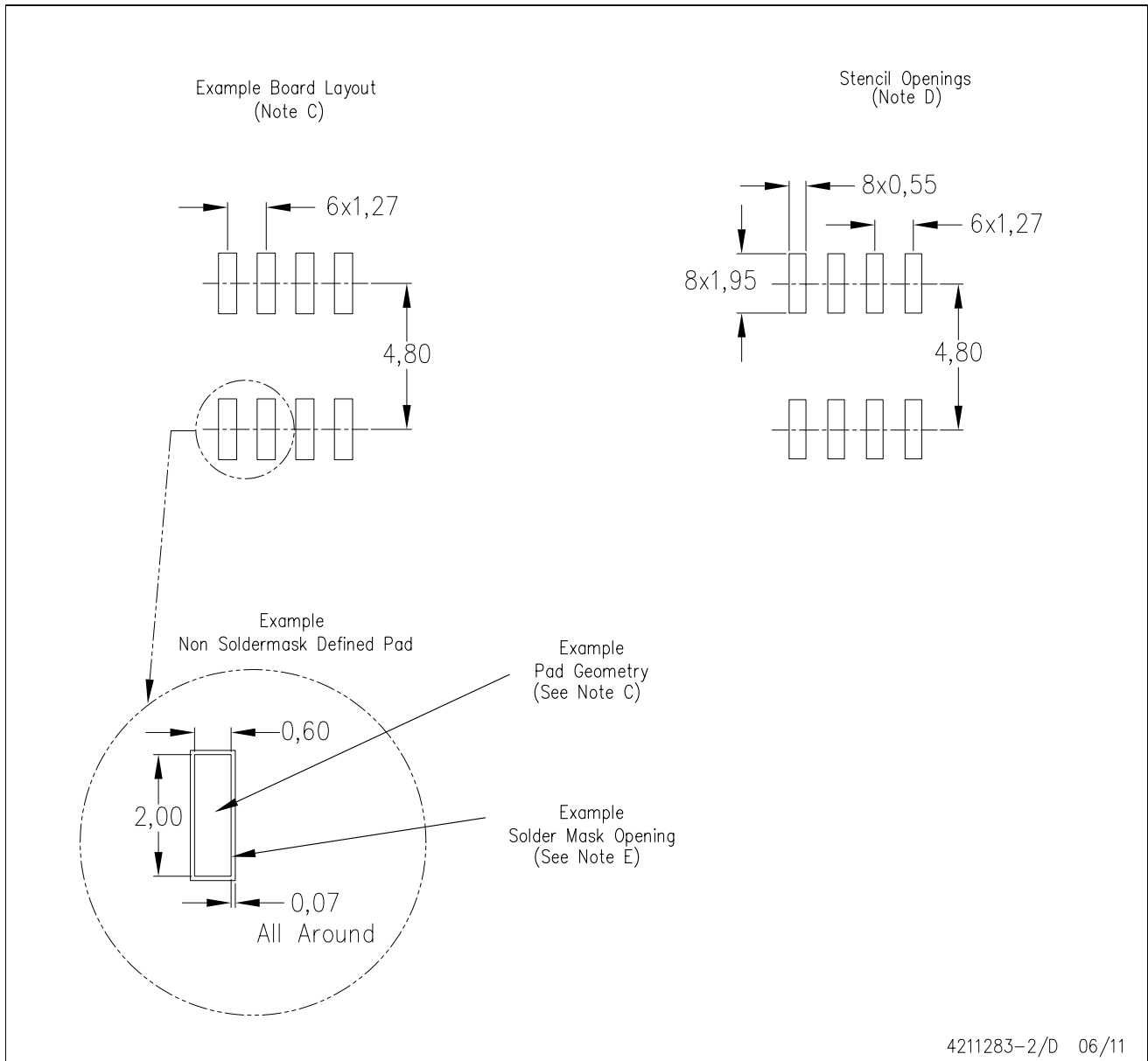


4040064-7/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

D (R-PDSO-G8)

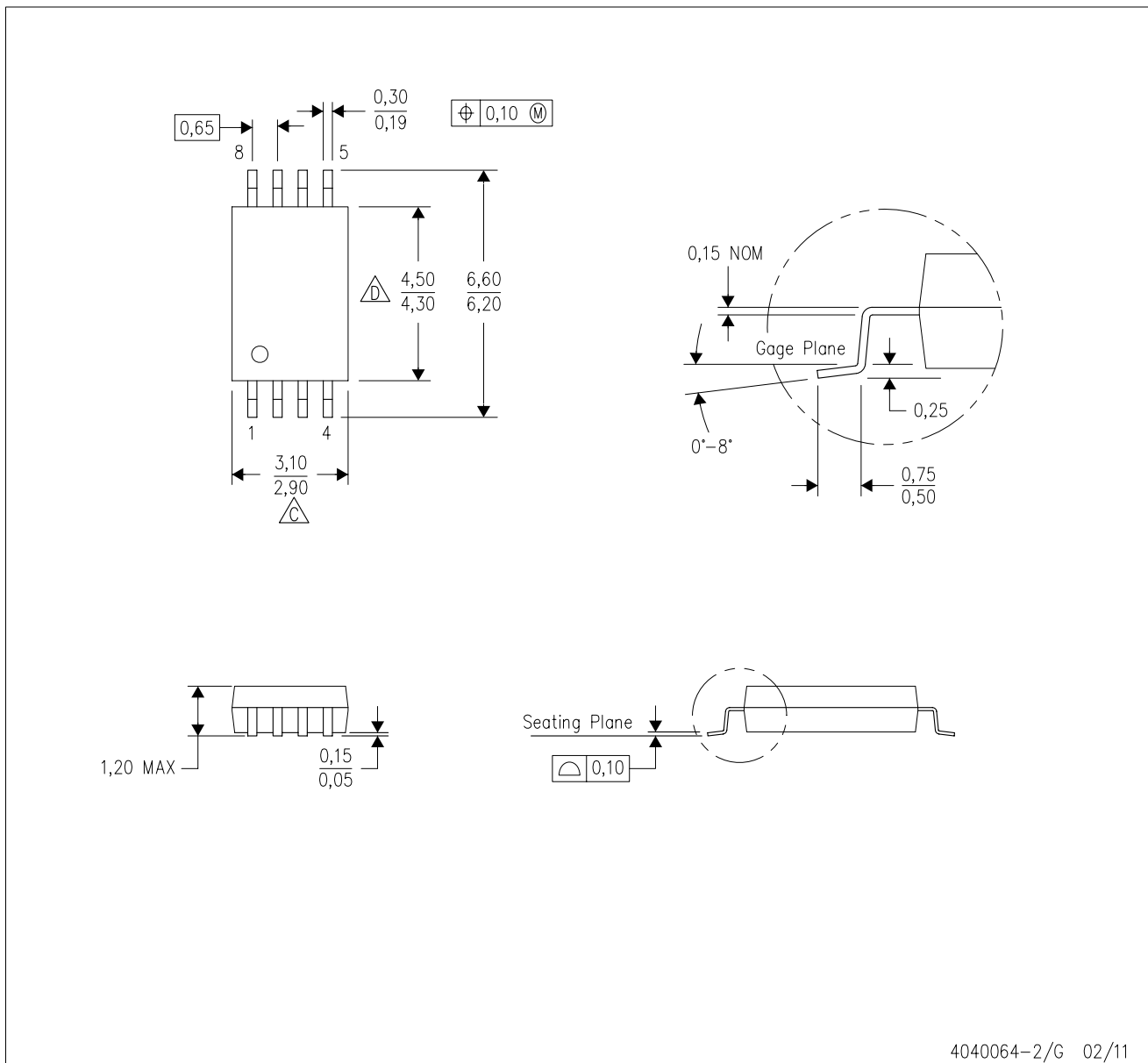
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4040064-2/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video
Wireless	www.ti.com/wireless-apps

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated